ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES INDUSTRIES	nockburn, Illinois, A	ll rights reserved un tions.	der both This d	locument parts, the	is a declaration declaration en	on of the substand compasses all lo	es within the manufactur wer level materials for w	er listed ite hich the ma	em. Note: if t anufacturer h	he item is an as as engineering	sembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials an				als and Mf	and Mfg Information			
Supplier Information												
Company name* Company unique ID			Unique ID Authority				Response Date*					
onsemi	emi							2024-04-25				
Contact Name	Title - Contact			Phone - Contact*				Email - Contact*				
Product-Env-Stewards	luct-Env-Stewards Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
uthorized Representative* Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number Mf	r Item Number	Mfr Item Name		E	ffective Date	Version	Manufacturing Site		Veight*	UOM	Unit Type	
FA	N251030MNTXG	251030MNTXG 35A Voltage Mode Buck Regulator wit		nc 20	024-04-25		PBB	9	4.792	mg	Each	
Manufacturing Proccess Information												
Terminal Plating / Grid Array Material	Grid Array Material Terminal Base Alloy		STD-020 MSL Ratin	ıg	Peak Proce	ss Body Tempera	ature Max Time at Peak	Temperatu	ire Number	of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU Alloy 1				260	С	30	second	ls 3				
Comments												
level 1 - maximum time at peak temperature duri	ing soldering is 10-3	0 seconds										
For more information regarding material compos	sition please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibisobutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier rot a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of hat agreement, will be the sole and exclusivesource of the Supplier's Iiability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies o										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	3.85	mg	Supplier	Zinc (Zn)	7440-66-6		0.0046	mg
			Supplier	Iron (Fe)	7439-89-6		0.0924	mg
			Supplier	Copper (Cu)	7440-50-8		3.7499	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0031	mg
Die	3.002	mg	Supplier	Silicon (Si)	7440-21-3		3.002	mg
Ероху	0.08	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.0064	mg
			Supplier	Proprietary	Proprietary Data		0.0072	mg
			Supplier	Bismaleimide	13676-54-5		0.0216	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.0008	mg
			Supplier	PTFE	9002-84-0		0.044	mg
Lead Frame	39.91	mg	Supplier	Silver (Ag)	7440-22-4		1.9955	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0479	mg
			Supplier	Iron (Fe)	7439-89-6		0.9578	mg
			Supplier	Copper (Cu)	7440-50-8		36.8768	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0319	mg
Mold Compound-Black	38.3	mg		Proprietary	proprietary data		3.064	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1915	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		35.0445	mg
Plating	3.81	mg	Supplier	Tin (Sn)	7440-31-5		3.81	mg
Solder Paste	5.26	mg	Supplier	Silver (Ag)	7440-22-4		0.1315	mg
			А	Lead (Pb)	7439-92-1	7a	4.8655	mg
			Supplier	Tin (Sn)	7440-31-5		0.263	mg
Wire Bond - Au	0.58	mg	Supplier	Gold (Au)	7440-57-5		0.58	mg